

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

**Title of
Invention****METHOD FOR FABRICATING SEMICONDUCTOR PACKAGES, AND
LEADFRAME ASSEMBLIES FOR THE FABRICATION THEREOF**

Application Type: regular, utility

Attorney Docket Number: 27-021

Correspondence address:

Customer Number:

22898

22898

Inventors Information:**Inventor 1:**

Applicant Authority Type: Inventor
Citizenship: KR
Given Name: Byung Joon
Family Name: HAN
City of Residence: Singapore
Country of Residence: SG
Address-1 of Mailing Address: 5 Yishun Street 23
Address-2 of Mailing Address:
City of Mailing Address: Singapore
State of Mailing Address:
Postal Code of Mailing Address: 768442
Country of Mailing Address: SG
Phone:
Fax:
E-mail:

Inventor 2:

Applicant Authority Type: Inventor
Citizenship: KR
Given Name: Byung Hoon

Family Name: AHN
City of Residence: Singapore
Country of Residence: SG
Address-1 of Mailing Address: 5 Yishun Street 23
Address-2 of Mailing Address:
City of Mailing Address: Singapore
State of Mailing Address:
Postal Code of Mailing Address: 768442
Country of Mailing Address: SG
Phone:
Fax:
E-mail:

Attorney Information:

practitioner(s) at Customer Number:

22898 *22898*

as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Publication Information:

Suggested Figure for Publication – FIG. 8

Suggested Classification –

Suggested Technology Center –

Total Number of Drawing Sheets – 5

Assignee 1:

Organization Name: ST ASSEMBLY TEST SERVICES LTD.

Address-1 of Mailing Address: 5 Yishun St. 23

Address-2 of Mailing Address:

City of Mailing Address: Singapore

State of Mailing Address:

Postal Code of Mailing Address:

Country of Mailing Address: SG

Phone:

Fax:

E-mail: